NCE N-Channel Enhancement Mode Power MOSFET

Description

The NCE2060K uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

General Features

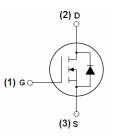
- V_{DS} =20V,I_D =60A
 - $R_{DS(ON)}$ <8m Ω @ V_{GS} =4.5V
- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high E_{AS}
- Excellent package for good heat dissipation

Application

- Load switching
- Hard switched and high frequency circuits
- Uninterruptible power supply

100% UIS TESTED!

100% ΔVds TESTED!



Schematic diagram



Marking and pin assignment



TO-252-2L top view

Package Marking and Ordering Information

| Device Marking | Device | Device Package | Reel Size | Tape width | Quantity |
|----------------|----------|----------------|-----------|------------|----------|
| NCE2060K | NCE2060K | TO-252-2L | - | - | - |

Absolute Maximum Ratings (T_C=25 ℃ unless otherwise noted)

| Parameter | Symbol | Limit | Unit |
|--|------------------------|------------|------------|
| Drain-Source Voltage | VDS | 20 | V |
| Gate-Source Voltage | V _G s | ±12 | V |
| Drain Current-Continuous | I _D | 60 | А |
| Drain Current-Continuous(T _C =100 °C) | I _D (100°C) | 42 | Α |
| Pulsed Drain Current | I _{DM} | 210 | Α |
| Maximum Power Dissipation | P _D | 60 | W |
| Derating factor | | 0.48 | W/℃ |
| Single pulse avalanche energy (Note 5) | E _{AS} | 200 | mJ |
| Operating Junction and Storage Temperature Range | T_J, T_{STG} | -55 To 150 | $^{\circ}$ |



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Thermal Characteristic

| Thermal Resistance, Junction-to-Case (Note 2) | R ₀ JC | 2.1 | °C/W | 1 |
|---|-------------------|-----|------|---|
|---|-------------------|-----|------|---|

Electrical Characteristics (T_C=25°C unless otherwise noted)

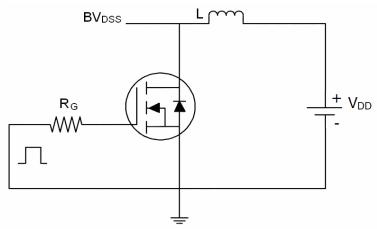
| Parameter | Symbol | Condition | Min | Тур | Max | Unit |
|------------------------------------|---------------------|--|-----|------|------|------|
| Off Characteristics | | | • | | | |
| Drain-Source Breakdown Voltage | BV _{DSS} | V _{GS} =0V I _D =250μA | 20 | - | - | V |
| Zero Gate Voltage Drain Current | I _{DSS} | V _{DS} =20V,V _{GS} =0V | - | - | 1 | μA |
| Gate-Body Leakage Current | I _{GSS} | V _{GS} =±12V,V _{DS} =0V | - | - | ±100 | nA |
| On Characteristics (Note 3) | | | | | | |
| Gate Threshold Voltage | V _{GS(th)} | V _{DS} =V _{GS} ,I _D =250μA | 0.5 | 0.8 | 1.4 | V |
| Drain-Source On-State Resistance | В | V _{GS} =4.5V, I _D =20 A | - | 5.5 | 8 | mΩ |
| Diam-Source On-State Resistance | R _{DS(ON)} | V _{GS} =4.5V, I _D =20 A V _{GS} =2.5V, I _D =15A V _{DS} =10V,I _D =20A V _{DS} =10V,V _{GS} =0V, | | 8 | 11 | mΩ |
| Forward Transconductance | G FS | V _{DS} =10V,I _D =20A | 15 | - | - | S |
| Dynamic Characteristics (Note4) | | | | | | |
| Input Capacitance | C _{lss} | \/ =10\/\/ =0\/ | - | 2000 | - | PF |
| Output Capacitance | Coss | V _{DS} =10V,V _{GS} =0V, F=1.0MHz | - | 500 | - | PF |
| Reverse Transfer Capacitance | C _{rss} | F-1.UIVITZ | - | 200 | - | PF |
| Switching Characteristics (Note 4) | | | | | | |
| Turn-on Delay Time | t _{d(on)} | | - | 6.4 | - | nS |
| Turn-on Rise Time | t _r | V_{DD} =10V, I_D =2A, R_L =1 Ω | - | 17.2 | - | nS |
| Turn-Off Delay Time | t _{d(off)} | V_{GS} =4.5 V , R_{G} =3 Ω | - | 29.6 | - | nS |
| Turn-Off Fall Time | t _f | | - | 16.8 | - | nS |
| Total Gate Charge | Q_g | \/ -40\/ L -20A | - | 27 | | nC |
| Gate-Source Charge | Q_{gs} | $V_{DS}=10V,I_{D}=20A,$ $V_{GS}=10V$ | - | 6.5 | | nC |
| Gate-Drain Charge | Q_{gd} | V GS-10 V | - | 6.4 | | nC |
| Drain-Source Diode Characteristics | | | | | | |
| Diode Forward Voltage (Note 3) | V _{SD} | V _{GS} =0V,I _S =10A | - | | 1.2 | V |
| Diode Forward Current (Note 2) | Is | | - | - | 60 | Α |
| Reverse Recovery Time | t _{rr} | TJ = 25°C, IF = 20A | - | 25 | - | nS |
| Reverse Recovery Charge | Qrr | di/dt = 100A/µs ^(Note3) | - | 24 | - | nC |
| Forward Turn-On Time | ton | Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD) | | | | |

Notes:

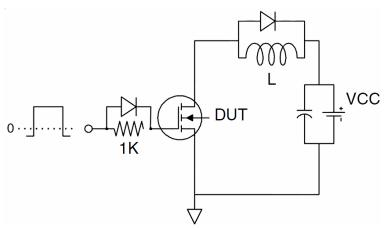
- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- **3.** Pulse Test: Pulse Width ≤ 300μ s, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to production
- **5.** E_{AS} condition : Tj=25 $^{\circ}$ C,V_{DD}=10V,V_G=10V,L=0.5mH,Rg=25 Ω ,

Test circuit

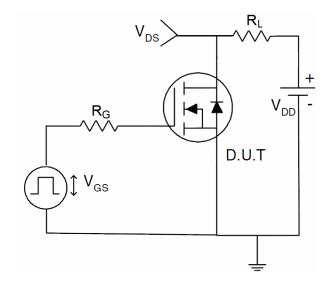
1) E_{AS} Test Circuit



2) Gate Charge Test Circuit



3) Switch Time Test Circuit



Pb Free Product



Typical Electrical and Thermal Characteristics (Curves)

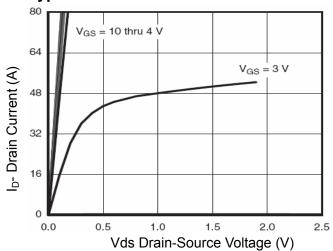


Figure 1 Output Characteristics

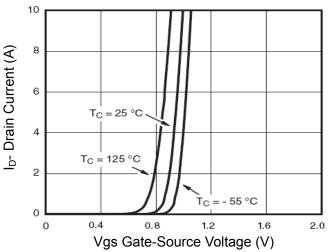


Figure 2 Transfer Characteristics

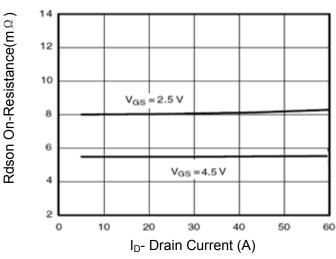


Figure 3 Rdson- Drain Current

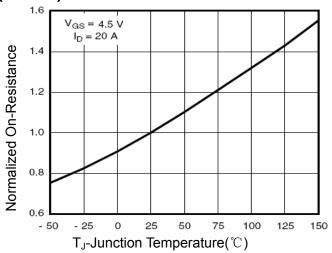


Figure 4 Rdson-JunctionTemperature

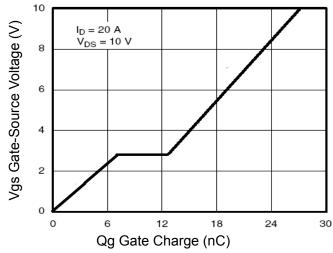


Figure 5 Gate Charge

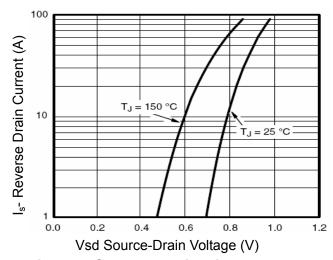


Figure 6 Source- Drain Diode Forward



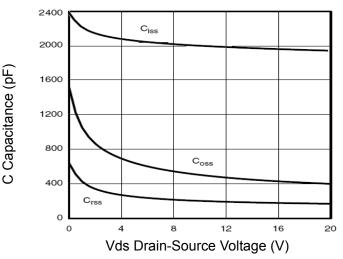


Figure 7 Capacitance vs Vds

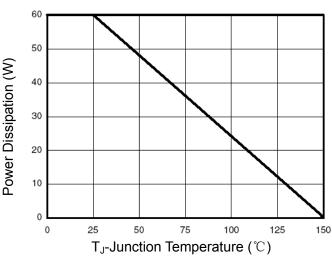


Figure 9 Power De-rating

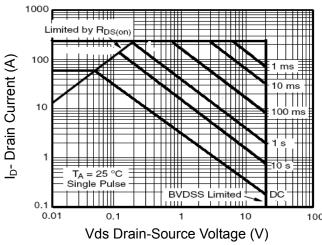


Figure 8 Safe Operation Area

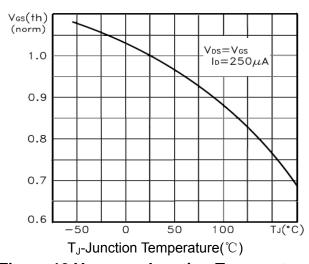


Figure 10 V_{GS(th)} vs Junction Temperature

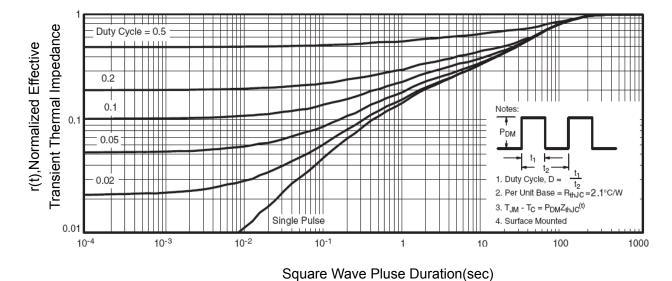
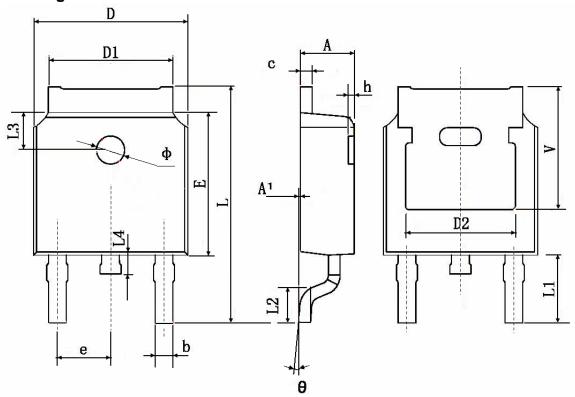


Figure 11 Normalized Maximum Transient Thermal Impedance

TO-252 Package Information



| Complete | Dimensions | In Millimeters | Dimensions In Inches | | |
|----------|------------|----------------|----------------------|-------|--|
| Symbol | Min. | Max. | Min. | Max. | |
| А | 2.200 | 2.400 | 0.087 | 0.094 | |
| A1 | 0.000 | 0.127 | 0.000 | 0.005 | |
| b | 0.660 | 0.860 | 0.026 | 0.034 | |
| С | 0.460 | 0.580 | 0.018 | 0.023 | |
| D | 6.500 | 6.700 | 0.256 | 0.264 | |
| D1 | 5.100 | 5.460 | 0.201 | 0.215 | |
| D2 | 4.83 | 0 TYP. | 0.190 | TYP. | |
| Е | 6.000 | 6.200 | 0.236 | 0.244 | |
| е | 2.186 | 2.386 | 0.086 | 0.094 | |
| L | 9.800 | 10.400 | 0.386 | 0.409 | |
| L1 | 2.900 | TYP. | 0.114 | ГҮР. | |
| L2 | 1.400 | 1.700 | 0.055 | 0.067 | |
| L3 | 1.600 | TYP. | 0.063 | TYP. | |
| L4 | 0.600 | 1.000 | 0.024 | 0.039 | |
| Ф | 1.100 | 1.300 | 0.043 | 0.051 | |
| θ | 0° | 8° | 0° | 8° | |
| h | 0.000 | 0.300 | 0.000 | 0.012 | |
| V | 5.350 | TYP. | 0.211 TYP. | | |



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